

IN THE CLAIMS:

Please replace claims 3-10 as follows:

3. (Amended) A method as claimed in claim 1 wherein holes (12;39) are etched and filled with metal (13;40) to allow contacts to be made to the filters (2;28).

4. (Amended) A method as claimed in claim 1 wherein metal layers (44) are deposited on the edges of the filters (28) after they have been separated in order to allow contacts to be made to the filters.

5. (Amended) A method as claimed in claim 1 wherein a third wafer (14;34) is bonded to the first wafer (1;27) on that face remote from the second wafer (8;30).

6. (Amended) A method as claimed in claim 1 wherein one or more of the wafer bonding processes is undertaken under a vacuum.

7. (Amended) A method as claimed in claim 1 wherein one or more of the wafer bonding processes used is anodic bonding employing a borosilicate bonding layer.

8. (Amended) A method as claimed in claim 1 wherein one or more of the wafer bonding processes used employs a low melting point glass as the bonding layer and the bond is made by a combination of heat and pressure.

9. (Amended) A method as claimed in claim 1 wherein one or more of the wafer bonding processes used employs a metal or alloy as the bonding layer and the bond is made by a combination of heat and pressure.

10. (Amended) A filter made by the method according to claim 1.

REMARKS

Claims 1-14 are pending. By this Preliminary Amendment, the specification is amended to conform to U.S. patent practice and claims 3-10 are amended to eliminate multiple dependencies and a typographical error. Prompt and favorable consideration on the merits is respectfully requested.